

# MALS062

## Silicon planar type

For ESD protection

### ■ Features

- Electrostatic discharge ESD:  $\pm 30$  kV
- SS-Mini 2 pin molde type package, optimum for high-density mounting.

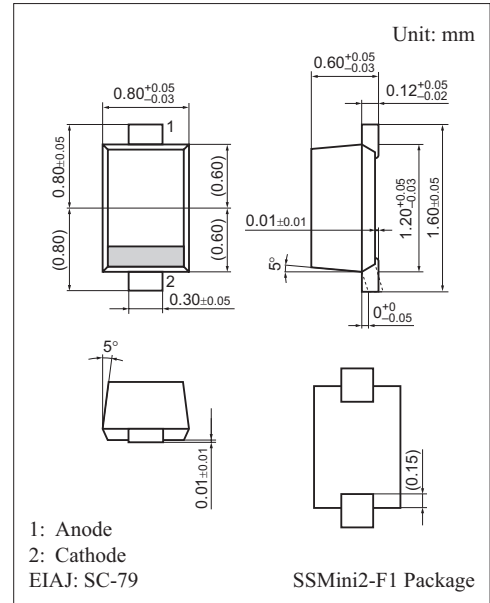
### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Total power dissipation *1	$P_T$	150	mW
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{\text{stg}}$	-55 to +150	$^\circ\text{C}$
Electrostatic discharge *2	ESD	$\pm 30$	kV

Note) \*1:  $P_T = 150$  mW achieved with a printed circuit board.

\*2: Test method: IEC61000-4-2

(C = 150 pF, R = 330  $\Omega$ , Contact discharge: 10 times)



Marking Symbol: DE

### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

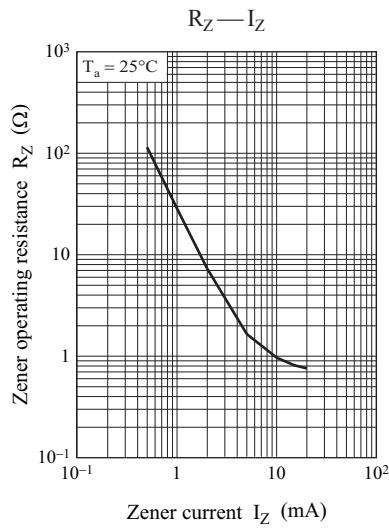
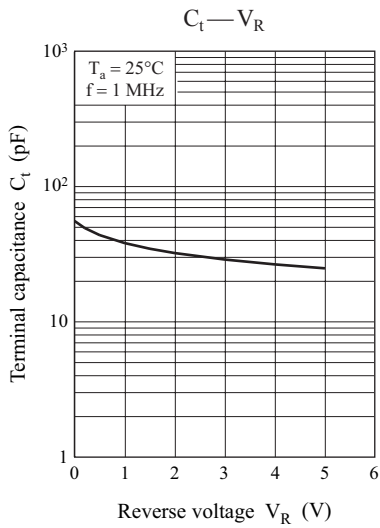
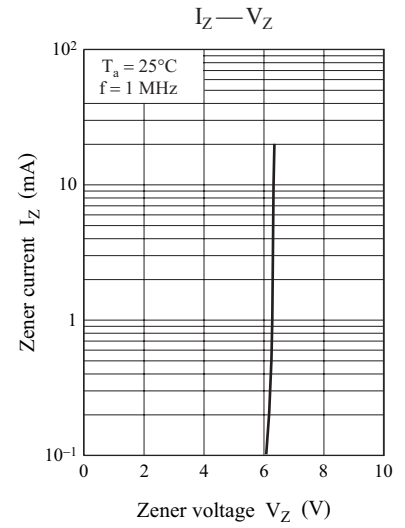
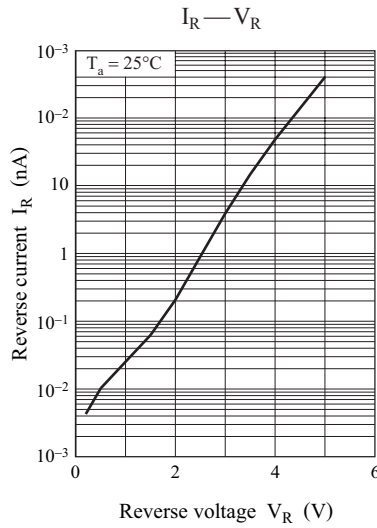
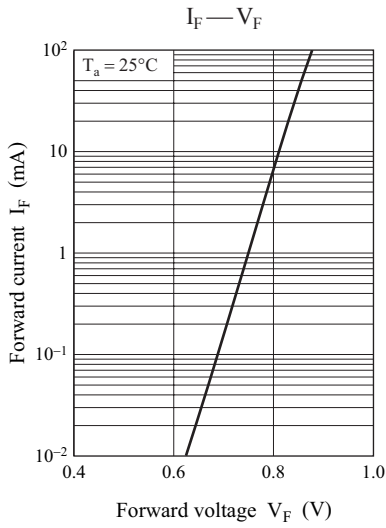
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Breakdown voltage *	$V_{BR}$	$I_Z = 1$ mA	5.8	6.2	6.6	V
Reverse current	$I_R$	$V_R = 4.0$ V			1.0	$\mu\text{A}$
Terminal capacitance	$C_t$	$V_R = 0$ V, $f = 1$ MHz		55		pF

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. The temperature must be controlled  $25^\circ\text{C}$  for  $V_{BR}$  measurement.

$V_{BR}$  value measured at other temperature must be adjusted to  $V_{BR}(25^\circ\text{C})$

3. \*:  $V_{BR}$  guaranteed 20 ms after current flow.



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